



# **MMDT5551**

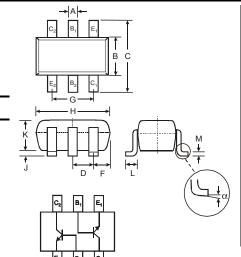
### **DUAL NPN SMALL SIGNAL SURFACE MOUNT TRANSISTOR**

## **Features**

- **Epitaxial Planar Die Construction**
- Complementary PNP Type Available (MMDT5401)
- Ideal for Medium Power Amplification and Switching
- Ultra-Small Surface Mount Package
- Lead Free/RoHS Compliant (Note 3)
- "Green" Device (Note 4 and 5)

### **Mechanical Data**

- Case: SOT-363
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Terminal Connections: See Diagram
- Marking Information: K4N, See Page 3
- Ordering & Date Code Information: See Page 3
- Weight: 0.006 grams (approximate)



SOT-363										
Dim	Min	Max								
Α	0.10	0.30								
В	1.15	1.35								
С	2.00	2.20								
D	0.65 N	ominal								
F	0.30	0.40								
Н	1.80	2.20								
J	_	0.10								
K	0.90	1.00								
L	0.25	0.40								
М	0.10	0.25								
α	0°	8°								
All Din	nensions	in mm								

## **Maximum Ratings** @TA = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit
Collector-Base Voltage		V <sub>CBO</sub>	180	V
Collector-Emitter Voltage		$V_{CEO}$	160	V
Emitter-Base Voltage		$V_{EBO}$	6.0	V
Collector Current - Continuous	(Note 1)	Ic	200	mA
Power Dissipation	(Note 1, 2)	$P_d$	200	mW
Thermal Resistance, Junction to Ambient	(Note 1)	$R_{ hetaJA}$	625	°C/W
Operating and Storage Temperature Range		T <sub>j</sub> , T <sub>STG</sub>	-55 to +150	°C

Notes:

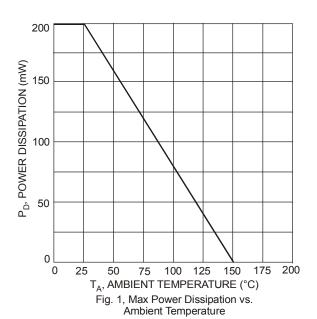
- 1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- Maximum combined dissipation.
- No purposefully added lead.
- Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead\_free/index.php.
- Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

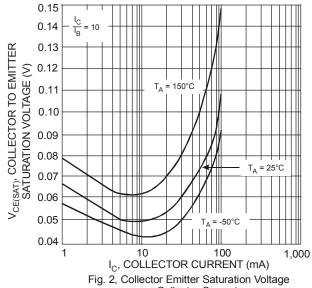


#### **Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

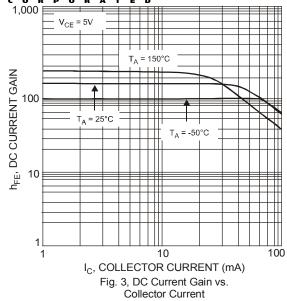
Characteristic	Symbol	Min	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)	<u>.</u>			•	
Collector-Base Breakdown Voltage	V <sub>(BR)CBO</sub>	180	_	V	$I_C = 100 \mu A, I_E = 0$
Collector-Emitter Breakdown Voltage	V <sub>(BR)CEO</sub>	160	_	V	I <sub>C</sub> = 1.0mA, I <sub>B</sub> = 0
Emitter-Base Breakdown Voltage	V <sub>(BR)EBO</sub>	6.0	_	V	$I_E = 10 \mu A, I_C = 0$
Collector Cutoff Current	I <sub>CBO</sub>	_	50	nA μA	V <sub>CB</sub> = 120V, I <sub>E</sub> = 0 V <sub>CB</sub> = 120V, I <sub>E</sub> = 0, T <sub>A</sub> = 100°C
Emitter Cutoff Current	I <sub>EBO</sub>	_	50	nA	V <sub>EB</sub> = 4.0V, I <sub>C</sub> = 0
ON CHARACTERISTICS (Note 6)					
DC Current Gain	h <sub>FE</sub>	80 80 30	250 —	_	$I_C = 1.0 \text{mA}, V_{CE} = 5.0 \text{V}$ $I_C = 10 \text{mA}, V_{CE} = 5.0 \text{V}$ $I_C = 50 \text{mA}, V_{CE} = 5.0 \text{V}$
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>	_	0.15 0.20	V	I <sub>C</sub> = 10mA, I <sub>B</sub> = 1.0mA I <sub>C</sub> = 50mA, I <sub>B</sub> = 5.0mA
Base-Emitter Saturation Voltage		_	1.0	V	I <sub>C</sub> = 10mA, I <sub>B</sub> = 1.0mA I <sub>C</sub> = 50mA, I <sub>B</sub> = 5.0mA
SMALL SIGNAL CHARACTERISTICS	·				
Output Capacitance	C <sub>obo</sub>	_	6.0	pF	V <sub>CB</sub> = 10V, f = 1.0MHz, I <sub>E</sub> = 0
Small Signal Current Gain	h <sub>fe</sub>	50	250	_	V <sub>CE</sub> = 10V, I <sub>C</sub> = 1.0mA, f = 1.0kHz
Current Gain-Bandwidth Product	f <sub>T</sub>	100	300	MHz	V <sub>CE</sub> = 10V, I <sub>C</sub> = 10mA, f = 100MHz
Noise Figure	NF	_	8.0	dB	$V_{CE}$ = 5.0V, $I_{C}$ = 200μA, $R_{S}$ = 1.0kΩ, $f$ = 1.0kHz

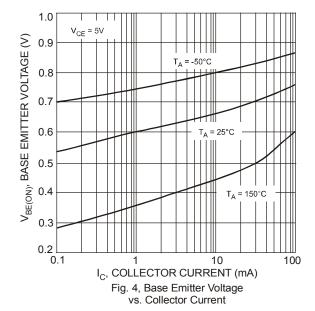
Notes: 6. Short duration pulse test used to minimize self-heating effect.

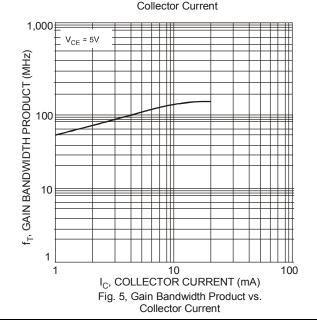










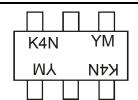


## Ordering Information (Note 7)

ĺ	Device	Packaging	Shipping		
	MMDT5551-7-F	SOT-363	3000/Tape & Reel		

Notes: 7. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

## **Marking Information**



K4N = Product Type Marking Code YM = Date Code Marking Y = Year ex: N = 2002 M = Month ex: 9 = September

Date Code Key

Date Code Ney															
Year	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012
Code	J	K	L	М	Ν	Р	R	S	Т	U	V	W	X	Υ	Z

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



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